



RS1A/B - RS1M/B

1.0A SURFACE MOUNT FAST RECOVERY RECTIFIER

Features

- Glass Passivated Die Construction
- · Fast Recovery Time for High Efficiency
- Surge Overload Rating to 30A Peak
- Ideally Suited for Automated Assembly
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SMA/SMB
- Case Material: Molded Plastic.
 - UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Alloy Leadframe; Solderable per MIL-STD-202, Method 208 63
- Polarity: Cathode Band or Cathode Notch
- Weight: SMA 0.064 grams (Approximate)

SMB - 0.093 grams (Approximate)

SMA/SMB





Top View

Bottom Vie

Ordering Information (Note 4)

Part Number	Case	Packaging
RS1x-13-F	SMA	5,000/Tape & Reel
RS1xB-13-F	SMB	3,000/Tape & Reel

^{*} x = Device type, e.g. RS1D-13-F (SMA package); RS1JB-13-F (SMB package).

otes: 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packing details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

SMA/SMB



RS1x = Product Type Marking Code, ex: RS1G (SMA Package)
RS1xB = Product Type Marking Code, ex: RS1GB (SMB Package)
J!!= Manufacturer's Code Marking
YWW = Date Code Marking
Y = Last Digit of Year (ex: 4 for 2014)
WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	RS1 A/AB	RS1 B/BB	RS1 D/DB	RS1 G/GB	RS1 J/JB	RS1 K/KB	RS1 M/MB	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 5)	$egin{array}{c} V_{RRM} \ V_{RWM} \ V_{R} \end{array}$	50	100	200	400	600	800	1,000	>
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @ T _T = +120°C	lo				1.0				Α
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load					30				Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 6)	$R_{ heta JT}$	20	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-65 to +150	°C

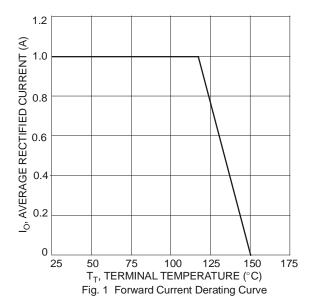
Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

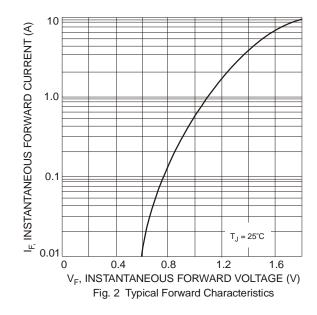
Characteristic		Symbol	RS1 A/AB	RS1 B/BB	RS1 D/DB	RS1 G/GB	RS1 J/JB	RS1 K/KB	RS1 M/MB	Unit
Minimum Reverse Breakdown Voltage (Note 5)	@ $I_R = 0.5 \mu A$	$V_{(BR)R}$	50	100	200	400	600	800	1,000	V
Maximum Forward Voltage Drop	$@ I_F = 1.0A$	V_{FM}				1.3				V
Peak Reverse Current	@ $T_A = +25^{\circ}C$	lou				5.0				μA
at Rated DC Blocking Voltage (Note 5)	@ $T_A = +125^{\circ}C$	I _{RM}				200				μΛ
Maximum Reverse Recovery Time (Note 7)		t _{rr}		15	50		250	50	00	ns
Typical Total Capacitance (Note 8)	•	Ст		•		15		•		pF

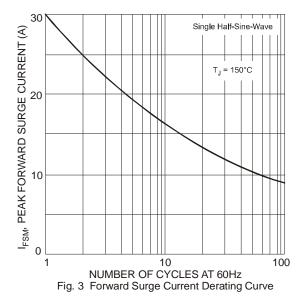
Notes:

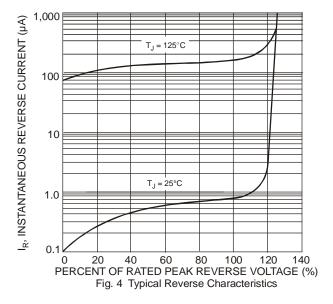
- 5. Short duration pulse test used to minimize self-heating effect. 6. Valid provided that terminals are kept at ambient temperature. 7. Reverse recovery test conditions: $I_F = 0.5A$, $I_R = 1.0A$, $I_{rr} = 0.25A$. See Figure 5. 8. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.













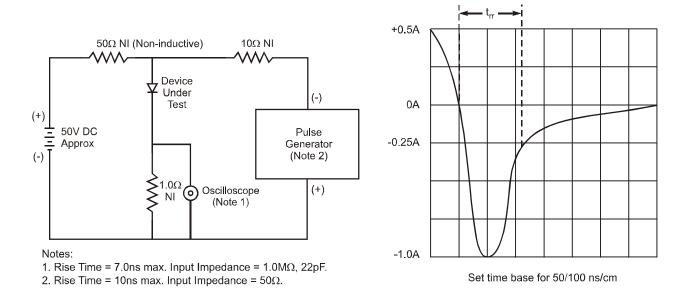
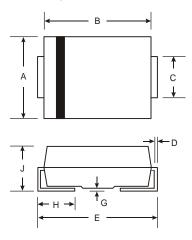


Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

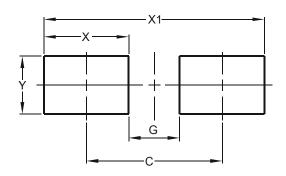


SMA				
Dim	Min	Max		
Α	2.29	2.92		
В	4.00	4.60		
C	1.27	1.63		
D	0.15	0.31		
Е	4.80	5.59		
G 0.05 0.20				
H 0.76 1.52				
7	1.96	2.40		
All Dimensions in mm				

SMB				
Dim	Min	Max		
Α	3.30	3.94		
В	4.06	4.57		
С	1.96	2.21		
D	0.15	0.31		
Е	5.00	5.59		
G	0.05	0.20		
Н	0.76	1.52		
J	2.00	2.50		
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



SMA

Dimensions	Value (in mm)			
С	4.00			
G	1.50			
Х	2.50			
X1	6.50			
Y	1.70			

SMB

Dimensions	Value (in mm)
C	4.30
G	1.80
Х	2.50
X1	6.80
Y	2.30



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